

assembly; and

a second fan suitable for passing air through the alternate passage.

2. (Canceled)

3. (Amended) The cooling assembly of claim 1 [2], wherein the alternate passage includes a conduit in communication with the isolation assembly.

4. (Unchanged) The cooling assembly of claim 1, and further comprising a heat sink operably coupled to the first component.

5. (Unchanged) The cooling assembly of claim 1, wherein the plurality of components are enclosed within a case, and the air is drawn from outside the case.

6. (Unchanged) The cooling assembly of claim 1, wherein the plurality of components are enclosed within a case, and the air is drawn from within the case.

32. The cooling assembly of claim 4, wherein the heat sink comprises a passive heat sink.

33. The cooling assembly of claim 1, wherein the isolation assembly is configured to shield the first component from an amount of electromagnetic interference.

34. (Amended) A cooling assembly for at least one board, the at least one board suitable for accepting a plurality of components including a first component, the cooling assembly comprising:

a passage;

a first fan suitable for passing air through the passage; [and]

an isolation assembly for generally enclosing heat generated from the first component, wherein the first component is enclosed within the isolation assembly, the

isolation assembly in communication with the passage, and wherein the passage is separate from another heat-sensitive component within a [the] computer case;
an alternate passage configured to provide an air flow path to the isolation assembly; and
a second fan suitable for passing air through the alternate passage.

35. (Canceled)

36. (Amended) The cooling assembly of claim 34 [35], wherein the alternate passage includes a conduit in communication with the isolation assembly.

37. The cooling assembly of claim 34, and further comprising a heat sink operably coupled to the first component.

38. The cooling assembly of claim 34, wherein the plurality of components are enclosed within a case, and the air is drawn from outside the case.

39. The cooling assembly of claim 34, wherein the plurality of components are enclosed within a case, and the air is drawn from within the case.

40. The cooling assembly of claim 37, wherein the heat sink comprises a passive heat sink.

41. The cooling assembly of claim 34, wherein the isolation assembly is configured to shield the first component from an amount of electromagnetic interference.

42. (New) The cooling assembly of claim 1, wherein the first component comprises a processor.

43. (New) The cooling assembly of claim 34, wherein the first component comprises a processor.